

**S/N 10/823,314**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Neo C. Peng et al.

Examiner: Samuel M Heinrich

Serial No.: 10/823,314

Group Art Unit: 1725

Filed: April 13, 2004

Docket No.: 303.772US2

Title: WAFER DICING DEVICE AND METHOD

---

**AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

This paper responds to the Office Action mailed on February 11, 2008. Please amend the above-identified patent application as follows.